ID: 1319 **Reliability of electrodeposited components for fusion application** :A process evaluation of the first kind:



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ABSTRACT

- During the performance testing- Hot Helium Leak Test at 150 C and >25bars, for one of the accelerator grid for Diagnostic Neutral Beam (DNB), a failure across the Electrodeposited (ED) water to vacuum boundary was observed.
- This happens to be the first instance where an ED bond has been subjected to such severe test as per ITER spec. and this failure has triggered the necessity to undertake a systematic evaluation study to assess and establish the adhesion characteristics of such bonds, especially at operational temperature.
- Multiple ED samples, drawn from different ED bath, have been subjected to a specially designed test procedure, along with the other conventional mechanical and metallurgical tests, in order to arrive at an assessment of the strength parameters for the bond.

OUTCOME

Adhesion strength- Push test



• Hence, the present study is purported to present itself as a procedure for evaluation of this important manufacturing process. This is possibly first such initiative of its kind.

BACKGROUND



Adhesion strength- Modified Ollard test



Hardness profiles





Distance from Deposited Cu



While observing the location of the failure, it was inferred

that load of the plunger was actually resisted by the base

material rather than the intended CuED layer, and the



'All deposited' tensile strength

Electrolyte	25 C	150 C	150 C	150 C	150 C
ED 1	235	176	184	180	185
ED 2	304	214	217	221	218
ED 3	304	220	220	223	219
Raw Material	290	238	245	242	



'As manufactured 'angled' PG segment Failure during the Hot Helium Leak Test (150 C and >25bars) of Plasma Grid Segment of DNB (Right Picture shows the separation of ED layer from the base plate)

CHALLENGES / METHODS / IMPLEMENTATION

Challenges

No recommended procedure / historical database for carrying out an assessment of the bond integrity for electrodeposited surfaces and also no codes are presently available to qualify the process compatibility for the operational requirements including application at around 150 C.

Methods

- Adhesion Strength:
 - Push Test and Modified Ollard Test
- Hardness measurement
- **Optical Microscopy**
- Immersion Ultrasonic Testing
- All deposited sample tensile testing

Metallurgical investigation







Optical microstructure @

Deposited Surface

Optical microstructure (*a*) **Transverse cross section**

Immersion Ultrasonic Examination







ED2 @ 150 C

ED2 @ 25 C



ED3 @ 150 C ED3 @ 25 C

SUMMARY

Implementation







Plunger

ED Coppe

Adhesion test: Modified Ollard test



Test in-progress on Universal Testing Machine • A process has been established in form of experiments where ~20 samples, from different baths, have been subjected to tests to evaluate and obtain a statistical variation in the quality of the bond at room as well as at elevated temperature of 150 C.

• Test results shows the variation in the bond strengths is highly dependent on the bath quality • The results also establish that (1) it is mandatory to qualify the ED process according to the functional parameters and (2) it is equally important to qualify EACH bath, to ensure a reliable application of ED process for the actual components.

• Recommendation of the qualification process is as follows; (1) carrying out and interpreting the specially designed push test for samples (2) Co-relating the strength with the hardness parameters (3) study of microstructural characteristics and (4) application of process on production pieces.

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